

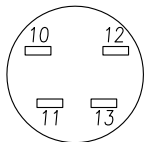
P.C.B Layout

SD CARD PIN DESIGN

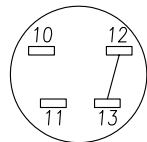
Pin No.	Name	Description
1#	CD/DAT3	Card detect/Data I/O
2#	CMD	Command
3#	VSS1	Ground
4#	VDD	Power
5#	CLK	Clock
6#	VSS2	Ground
7#	DAT0	Data I/O
8#	DAT1	Data I/O
9#	DAT2	Data I/O

NOTES:

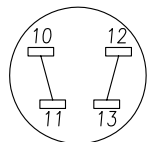
- MATERIAL
HOUSING: HIGH TEMPERATURE THERMOPLASTIC.
CONTACT: COPPER ALLOY.
SHELL: COPPER ALLOY.
- PLATING
CONTACT AREA: GOLD FLASH PLATED OVER Ni.
SOLDER TAIL: 100 u" MIN Sn/Pb PLATED OVER Ni.
SHELL SOLDER AREA: GOLD PLATED OVER Ni.
- RATING
CURRENT RATING: 0.5A
VOLTAGE RATING: 250VRMS
OPERATING TEMPERATURE: -25°C~90°C
- SPECIFICATION
CONTACT RESISTANCE: 40 Milliohms
DIELECTRIC WITHSTANDING VOLTAGE: 500VAC Megohms
INSULATION RESISTANCE: 100 Megohms
INSERTION FORCE: 40N MAX.
SEPARATION FORCE: 2N MIN.
- UNSPECIFIED TOLERANCE: .XXX ±0.10
.XX ±0.25
.X ±0.38



WITHOUT CARD



CARD INSERTED
WRITE PROTECT: LOCK



CARD INSERTED
WRITE PROTECT: UNLOCK

- 10--WRITE PROTECT PIN 1
- 11--WRITE PROTECT PIN 2
- 12--CARD DETECT PIN 1
- 13--CARD DETECT PIN 2

X MULTIPLE		CONNECTING THE INFORMATION AGE	
X MULTIPLE ASIA 4F, No. 347, Yang Guang St., Neihu Chiu, Taipei, Taiwan 11475		X MULTIPLE USA 543 Country Club Drive #B 128 Simi Valley, CA 93085	
THIS DRAWING IS A CONTROLLED DOCUMENT.		CUSTOMER/NO:	
TITLE: SECURE DIGITAL MEMORY CARD CONNECTOR, REVERSE TYPE WITH COVER		DWG NO: XSDC-3-09M1-KG00-10	
PART NO: XSDC-3-09M1-KG00-10		DRAWN: ANNIE	
		CHKD: JEFF	
		DATE: 09/11/04	
DIMENSIONS	SHEET	REV	
mm[inch]	1 of 1	01	